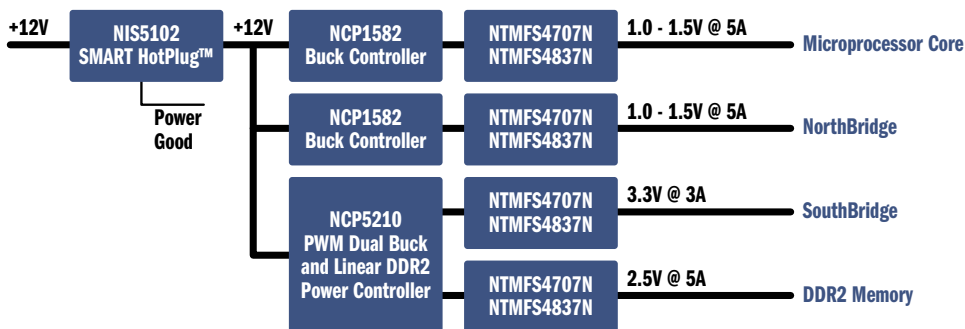


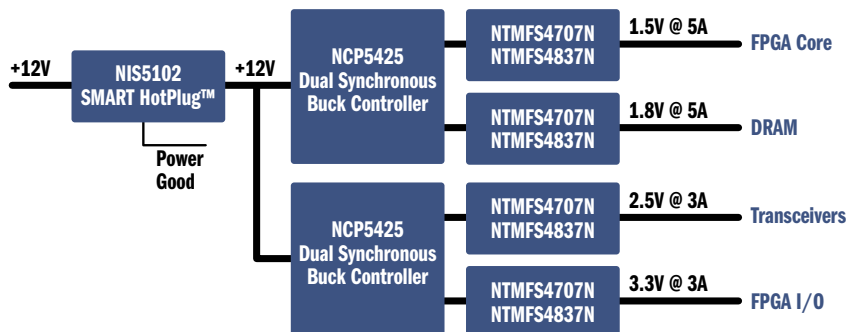
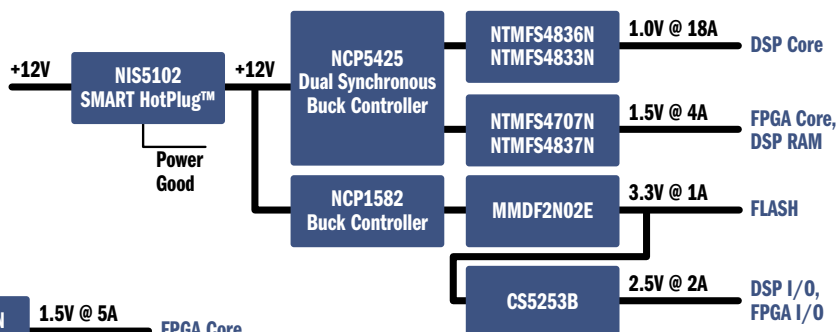
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Computing Card

Multi-DSP Card



Switch Fabric Card

Comprehensive Power Conversion Solutions for Mezzanine Cards in Routers, Switches and Base Stations

- **Highly Integrated Devices Reduce Part Count**
- **Robust Hot Swap Protection Includes Innovative MOSFET Temperature Sensing Shutdown**
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Presenting

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NIS5102 SMART HotPlug™ is a hot swap protection device for +12 V circuits. The combination of an integrated power MOSFET switch and a unique temperature-sensing capability makes this the most robust hot swap IC available. This highly integrated device also provides adjustable current limit with no external shunt required, undervoltage and overvoltage lockout, and a power good indicator.

NCP1582 Low Voltage Synchronous Buck Controller is a voltage mode PWM controller designed to operate from a 5 V or 12 V supply and produce an output voltage as low as 0.8 V. Features include a 0.7 A gate driver and an internally set 350 kHz oscillator. The NCP1582 also incorporates an externally compensated transconductance error amplifier and a programmable soft-start function. Protection features include short circuit protection (SCP) and under voltage lockout (UVLO).

NCP5210 3-In-1 PWM Dual Buck and Linear DDR Power Controller contains two synchronous PWM buck controller for driving four external N-Ch FETs to form the DDR memory supply voltage (VDDQ) and the MCH regulator. Protective features include, soft-start circuitry, undervoltage monitoring of 5VDUAL and BOOT voltage, and thermal shutdown.

NCP5425 Dual Synchronous Buck Controller is a highly flexible device with internal gate drivers that can provide two independent outputs or one high current output. This feature-rich controller offers adjustable switching frequency up to 750 kHz and a $\pm 1\%$ 0.8 V reference.

BILL OF MATERIALS

ON SEMICONDUCTOR DEVICE	PACKAGE	AVAILABILITY
NIS5102QP2HT1G	PDFN-12	Production
NCP1582DR2G	SOIC-8	Production
NCP5425DBG	TSSOP-20	Production
NCP5210MNR2G	QFN-20	Production
CS5253B-1GDPR5G	D2PAK	Production
NTMFS4707NT1G	SO-8FL	Production
NTMFS4833NT1G	SO-8FL	Production
NTMFS4836NT1G	SO-8FL	Production
NTMFS4837NT1G	SO-8FL	Production

